MC74AC540, MC74ACT540, MC74AC541, MC74ACT541

Octal Buffer/Line Driver with 3-State Outputs

The MC74AC540/74ACT540 and MC74AC541/74ACT541 are octal buffer/line drivers designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers. The MC74AC541/74ACT541 is a noninverting option of the MC74AC540/74ACT540.

These devices are similar in function to the MC74AC240/74ACT240 and MC74AC244/74ACT244 while providing flow−through architecture (inputs on opposite side from outputs). This pinout arrangement makes these devices especially useful as output ports for microprocessors, allowing ease of layout and greater PC board density.

Features

- 3−State Outputs
- Inputs and Outputs Opposite Side of Package, Allowing Easier Interface to Microprocessors
- Outputs Source/Sink 24 mA
- MC74AC540/74ACT540 Provides Inverted Outputs
- MC74AC541/74ACT541 Provides Noninverted Outputs
- ′ACT540 and ′ACT541 Have TTL Compatible Inputs
- These are Pb−Free Devices

TRUTH TABLE

Inputs			Outputs	
$\overline{OE}_1$	$\overline{OE}_2$	D	′540	′541
L	L	H	L	H
H	X	X	Z	Z
X	H	X	Z	Z
L	L	L	H	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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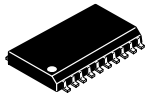
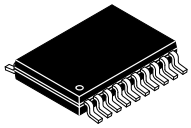

1

SOIC−20W
DW SUFFIX
CASE 751D


1

TSSOP−20
DT SUFFIX
CASE 948E

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 8 of this data sheet.

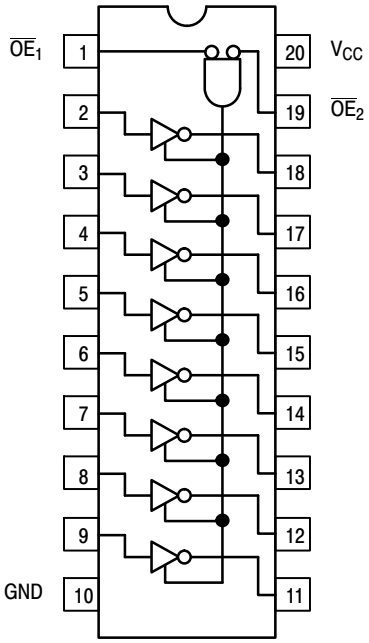


Figure 1. MC74AC540/74ACT540

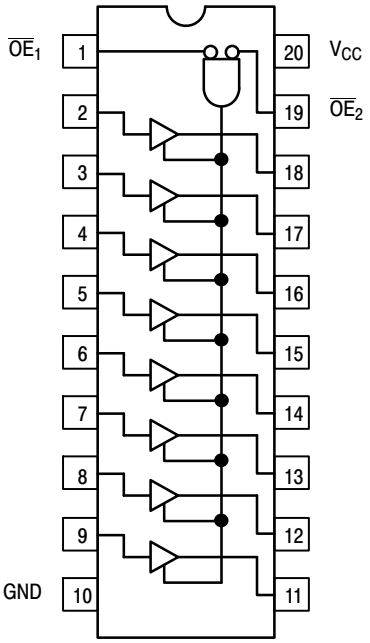


Figure 2. MC74AC541/74ACT541

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		−0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)		−0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND) (Note 1)		−0.5 to V_{CC} +0.5	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_{OUT}	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current, per Output Pin		±50	mA
I_{GND}	DC Ground Current, per Output Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		140	°C
θ_{JA}	Thermal Resistance (Note 2)	SOIC TSSOP	65.8 110.7	°C/W
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% − 35%	UL 94 V−0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latchup}$	Latchup Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_{OUT} absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JESD 51−7.
3. Tested to EIA/JESD22−A114−A.
4. Tested to EIA/JESD22−A115−A.
5. Tested to JESD22−C101−A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	−	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	−	150	−	ns/V
		V_{CC} @ 4.5 V	−	40	−	
		V_{CC} @ 5.5 V	−	25	−	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	−	10	−	ns/V
		V_{CC} @ 5.5 V	−	8.0	−	
T_A	Operating Ambient Temperature Range		−40	25	85	°C
I_{OH}	Output Current − High		−	−	−24	mA
I_{OL}	Output Current − Low		−	−	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C Typ	74AC T_A = −40°C to +85°C Guaranteed Limits		Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = −50 μA
		3.0 4.5 5.5	− − −	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} −12 mA I_{OH} −24 mA −24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	− − −	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	−	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3-State Current	5.5	−	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	−	−	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	−	−	−75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	−	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms − See AND8277/D at www.onsemi.com)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = −40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output (′AC540)	3.3 5.0	1.5 1.5	5.5 4.0	7.5 6.0	1.0 1.0	8.0 6.5	ns	3−5
t_{PHL}	Propagation Delay Data to Output (′AC540)	3.3 5.0	1.5 1.5	5.0 4.0	7.0 5.5	1.0 1.0	7.5 6.0	ns	3−5
t_{PZH}	Output Enable Time (′AC540)	3.3 5.0	3.0 2.0	8.5 6.5	11 8.5	2.5 2.0	12 9.5	ns	3−7
t_{PZL}	Output Enable Time (′AC540)	3.3 5.0	2.5 2.0	7.5 6.0	10 7.5	2.0 1.5	11 8.5	ns	3−8
t_{PHZ}	Output Disable Time (′AC540)	3.3 5.0	2.5 1.5	8.5 7.5	13 10.5	1.5 1.0	14 11	ns	3−7
t_{PLZ}	Output Disable Time (′AC540)	3.3 5.0	2.0 1.5	7.0 6.0	10 8.0	2.0 1.5	11 9.0	ns	3−8
t_{PLH}	Propagation Delay Data to Output (′AC541)	3.3 5.0	2.0 1.5	5.5 4.0	8.0 6.0	1.5 1.0	9.0 6.5	ns	3−5
t_{PHL}	Propagation Delay Data to Output (′AC541)	3.3 5.0	2.0 1.5	5.5 4.0	8.0 6.0	1.5 1.0	8.5 6.5	ns	3−5
t_{PZH}	Output Enable Time (′AC541)	3.3 5.0	3.0 2.0	8.0 6.0	11.5 8.5	3.0 1.5	12.5 9.5	ns	3−7
t_{PZL}	Output Enable Time (′AC541)	3.3 5.0	2.5 1.5	7.0 5.5	10 7.5	2.5 1.0	11.5 8.5	ns	3−8
t_{PHZ}	Output Disable Time (′AC541)	3.3 5.0	3.5 2.0	9.0 7.0	12.5 9.5	2.5 1.0	14 10.5	ns	3−7
t_{PLZ}	Output Disable Time (′AC541)	3.3 5.0	2.5 2.0	6.5 5.5	9.5 7.5	2.0 1.0	10.5 8.5	ns	3−8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C	74ACT T_A = −40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = −50 μA
		4.5 5.5	− −	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} −24 mA −24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	− −	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	−	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	−	1.5	mA	V_I = V_{CC} − 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	−	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	−	−	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	−	−	−75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	−	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms − See AND8277/D at www.onsemi.com)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = −40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output (′ACT540)	5.0	1.0	−	7.0	1.0	7.5	ns	3−5
t_{PHL}	Propagation Delay Data to Output (′ACT540)	5.0	1.0	−	8.0	1.0	8.5	ns	3−5
t_{PZH}	Output Enable Time (′ACT540)	5.0	1.0	−	10.5	1.0	11.5	ns	3−7
t_{PZL}	Output Enable Time (′ACT540)	5.0	1.0	−	9.5	1.0	10.5	ns	3−8
t_{PHZ}	Output Disable Time (′ACT540)	5.0	1.0	−	12.0	1.0	12.5	ns	3−7
t_{PLZ}	Output Disable Time (′ACT540)	5.0	1.5	−	9.0	1.0	10	ns	3−8
t_{PLH}	Propagation Delay Data to Output (′ACT541)	5.0	1.5	−	7.5	1.0	8.0	ns	3−5
t_{PHL}	Propagation Delay Data to Output (′ACT541)	5.0	1.5	−	7.5	1.0	8.0	ns	3−5
t_{PZH}	Output Enable Time (′ACT541)	5.0	2.0	−	10.0	1.0	11.0	ns	3−7
t_{PZL}	Output Enable Time (′ACT541)	5.0	1.5	−	9.5	1.0	10.5	ns	3−8
t_{PHZ}	Output Disable Time (′ACT541)	5.0	2.0	−	11.0	1.0	12.0	ns	3−7
t_{PLZ}	Output Disable Time (′ACT541)	5.0	2.0	−	9.0	1.0	10	ns	3−8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

ORDERING INFORMATION

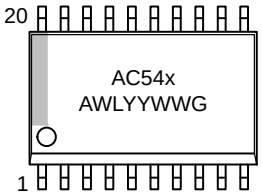
Device	Package	Shipping†
MC74AC540DWG	SOIC−20 (Pb−Free)	38 Units / Rail
MC74AC540DWR2G	SOIC−20 (Pb−Free)	1000 / Tape & Reel
MC74ACT540DWG	SOIC−20 (Pb−Free)	38 Units / Rail
MC74ACT540DWR2G	SOIC−20 (Pb−Free)	1000 / Tape & Reel
MC74ACT540DTR2G	TSSOP−20 (Pb−Free)	2500 / Tape & Reel
MC74AC541DWG	SOIC−20 (Pb−Free)	38 Units / Rail
MC74AC541DWR2G	SOIC−20 (Pb−Free)	1000 / Tape & Reel
MC74ACT541DWG	SOIC−20 (Pb−Free)	38 Units / Rail
MC74ACT541DWR2G	SOIC−20 (Pb−Free)	1000 / Tape & Reel
MC74AC541DTR2G	TSSOP−20 (Pb−Free)	2500 / Tape & Reel
MC74ACT541DTG	TSSOP−20 (Pb−Free)	75 Units / Rail
MC74ACT541DTR2G	TSSOP−20 (Pb−Free)	2500 / Tape & Reel

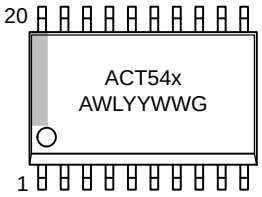
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*These packages are inherently Pb−Free.

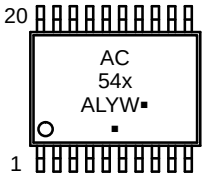
MARKING DIAGRAMS

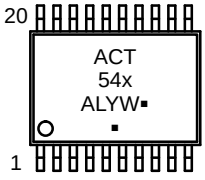
SOIC−20W





TSSOP−20



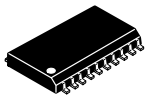


x	= 0 or 1
A	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week
G or ▪	= Pb−Free Package

(Note: Microdot may be in either location)

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

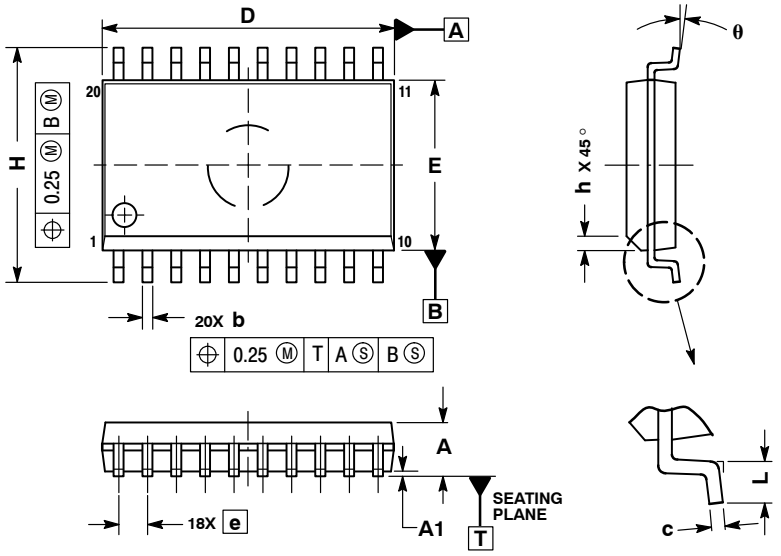
ON Semiconductor®



SCALE 1:1

SOIC–20 WB
CASE 751D–05
ISSUE H

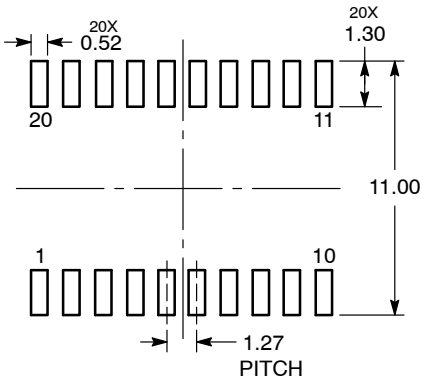
DATE 22 APR 2015



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

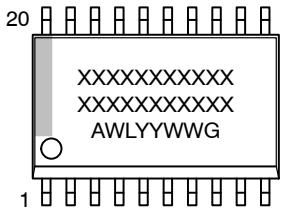
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “ ▪”, may or may not be present.

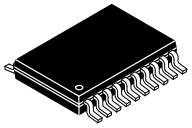
DOCUMENT NUMBER:	**98ASB42343B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**SOIC–20 WB**	**PAGE 1 OF 1**

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

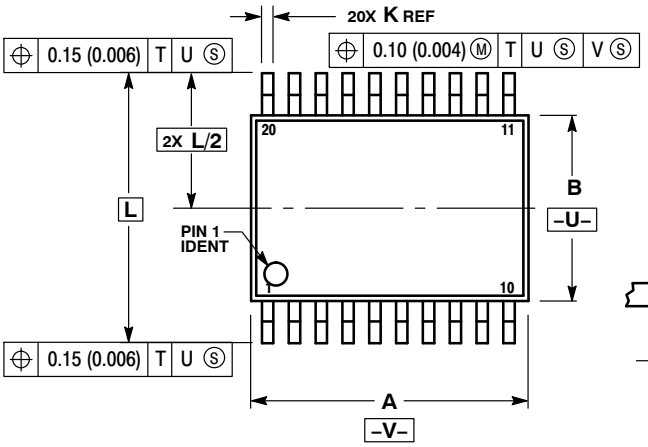
ON Semiconductor®

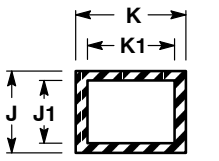
TSSOP−20 WB
CASE 948E
ISSUE D

DATE 17 FEB 2016

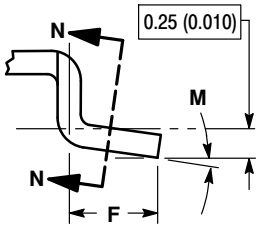


SCALE 2:1

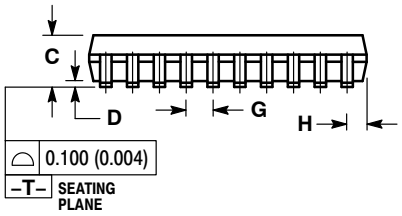


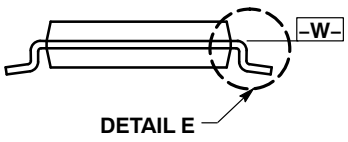


SECTION N−N



DETAIL E

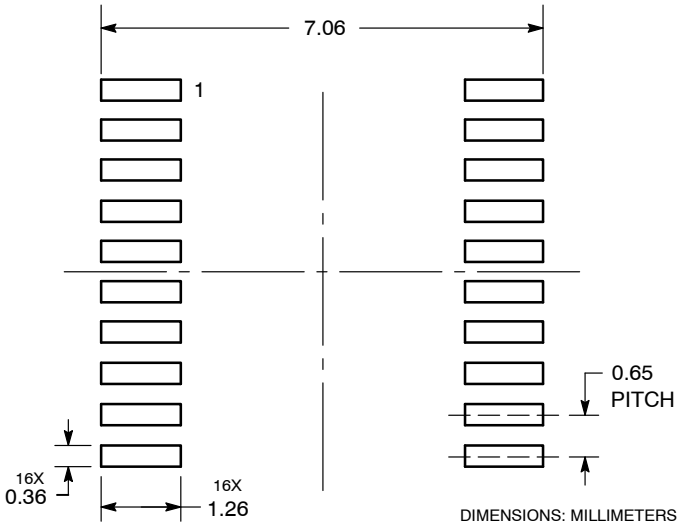




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

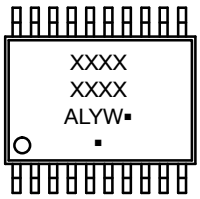
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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